

X-series SMT setup







Solder Joint Inspection

nt Power device PTH Cooling plate

Flexible High-Speed Inline AXI Platform

With the X-series platform Nordson Test & Inspection presents a dedicated high speed automatic X-ray inspection system concept for the inspection of PCB-assembly boards for single/multipanels or samples in trays. All solder joints of SMD and PTH components are covered by a dedicated AXI algorithm library.

The Nordson Test & Inspection system solutions present a modular inspection concept. The platforms feature up to 5 advance technologies in one system: Transmission X-ray imaging (2D) with patented Slice-Filter-Technique™ (SFT), Off-Axis technology (2.5D) and 3D SART (Simultaneous Algebraic Reconstruction Technique), Dynamic Planar CT.

The X-series platform is available in the following configurations:

X2.5 Transmission (2D) + SFT[™] + Off-Axis (2.5D)

X3 Transmission (2D) + SFT[™] + Off-Axis (2.5D) + 3D SART + Dynamic Planar CT

Inspection & Process Software

- PC-Station with multi-core processor setup
- Windows 10 platform
- MIPS 5 Inspection Platform
 - Advanced algorithm library
 - CAD import for automatic inspection list generation
 - Simultaneous Algebraic Reconstruction Technique
 (3D SART; X3 only) Dynamic Planar CT.
 - Machine Learning based" Automatic Tree
 Classification (ATC) for Auto-Rule-Generation
 - Offline programming for AXI program generation & simulation, tuning and defect reference catalogue
- Verification & Process control
 - MIPS Verify link with closed loop repair
 - MIPS Process with real time SPC

Features and Benefits

■ High Speed AXI system for inline setups

X2.5

- Microfocus X-ray tube (sealed tube / maintenance free)
- Multiple programmable motion system with linear motor axes
- Digital CMOS flatpanel detector
- Automatic grey-level and geometrical calibration
- Barcode scanner for serial number and product type selection
- Full product traceability via various MES Interfaces
- Industry 4.0 ready



X-series SMT setup

Applications

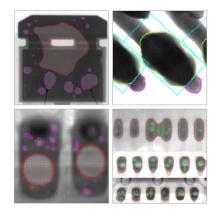
Electronic components and solder joint

A unique advanced algorithm library is available for electronic applications, specifically for component and solder-joint

inspection on PCB, hybrid or chip level assembly processes.

All standard IPC based SMD and THT/PTH components:

- QFN, QFP, PIP inspection
- Void inspection for Cooling plates
- HIP inspection for BGAs
- PTH and press fit component inspection



For more information, speak with your Nordson representative or contact your Nordson regional office

Nordson Test & Inspection Europe, SEA, Africa

ti-sales-eu@nordson.com

Nordson Test & Inspection Americas

ti-sales-us@nordson.com

Nordson Test & Inspection China

ti-sales-cn@nordson.com

Nordson Test & Inspection Japan

ti-sales-jp@nordson.com

Nordson Test & Inspection Singapore

ti-sales-eu@nordson.com

Nordson Test & Inspection

ti-sales-tw@nordson.com

Nordson Test & Inspection

ti-sales-korea@nordson.com

Specifications

Facilities		
Dimensions:	1630 mm (H) x 1800 mm (W) x 1575 mm (D)	
Adjustable conveyor height (SMEMA)	950 mm	
Weight:	2.800 kg	
Safe Operating Temperature:	15° - 28 °C optimal 20° - 25° C	
Power Consumption:	max. 6 kW	
Line Voltage:	400 VAC, 50/60 Hz 3 phase, 16 A/ 208 VAC, 50/60 Hz 3 phase, 25 A	
Air:	5-7 Bar, < 2 l/min, filtered (30μ), dry, oil free	

X-ray Image Chain		
X-ray Source (sealed tube)		
Energy:	SMT-Setup 130 kV/40 W	
Grey resolution:	14 Bit	
<u>Detector Types:</u>		
CMOS Flatpanel Detector	50 μm pixel size (6 MPix)	

Inspection features	
Max. sample size:	460 mm x 360 mm
Max. inspection area:	460 mm x 360 mm
Min. sample size	80 mm x 80 mm
Sample thickness	0,8-10 mm
Max. sample weight:	5 kg
Angle shot capability:	up to 50 deg
Resolution	3-4 μm/pix

Inspection speed		
Transmission (X2, X2.5, X3)	up to 6 views /s	
Off-Axis (X2.5, X3)	up to 5 views /s	
3D SART (X3)	up to 1 s /FoV	
Dynamic Planar CT (X3)	up to 3sec/ROI	

Motion System		
Multiple axes programmable motion system		
<u>Installed axes</u>		
x,y (linear drives)	sample table	
z (servo)	magnification	
u,v (linear drives)	detector movement	
<u>Conveyor setup</u>		
Inline set-up	automatic width adjustment	

Assembly clearance		
Topside (incl. sample thickness):	35/50 mm	
Bottom side (excl. sample thickness):	35/20 mm	
Min. edge clearance for clamping:	3 mm	

Included
Barcodereader
Low-dose radiation filter
UPS

